



Appl. No. 09/806,401
Amdt. Dated February 26, 2004
Reply to Office Action of August 26, 2003

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s) : Harry Hedler *et al.*
Application No. : 09/806,401
Filed : 10/22/2001
Title : ELECTRONIC MODULE, ESPECIALLY A MULTICHIP
MODULE, WITH MULTI-LAYER METALLIZATION AND
CORRESPONDING PRODUCTION METHOD
Group/Art Unit : 2827
Examiner : David E. Graybill
Docket No. : KSN0012

M/S FEE AMENDMENT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT

Sir:

In response to the Office Action of August 26, 2003, please amend the above-identified application as follows.

Amendments to the Claims are reflected in the listing of claims, which begins on page 2 of this paper.

Remarks/Arguments begin on page 4 of this paper.